GuangTu LEDTM

S PECI ICAT ION

Custome r	Pro duct	TO P Full-color LED
Customer No.	Туре	GT-3528URGB-RS





Tel: 0 755-23609023

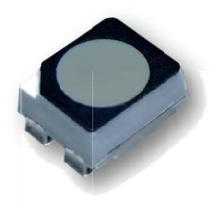
Fax: 0755-82591159

Code: 518000

R&D. RGB. NATIONSTAR			CUSTOMER		
APPROVE	CHE CK	CONFIRM			
Version NO: A4					
Releas e Date: 2015.04.20					

20150420TYBA4

3528-RGB-RS



These SMD LE Ds are pack aged in an in dustry standard PLCC4 package. These high reliability and high brightness LEDs are designed to work in a wide range of environmental conditions. A wide viewing angle and high brightness make these LE Ds suitable for indoor screen, decor ative lighting and amusement applications.

Fe atures		Application s
White Fram e with Blac k Surface	• Indoor	Full-color V ideo Screen
Multiple W aterproof	• Decora	tive Lightin g
Semi-glossy Surface	• Amuse	ment
High Lumin ous Intensi ty & High Re liability		
RoHS Co mpliant		
Pb-free Ref low Solderi ng Applicatio n		

1. SPECIFICATIO NS

1.1 Absolut e Maxim um Ratin gs ($T_A=25$ °C)

Item		Ra ing_			Unit
Item		Red	Green	Blue	Onic
Forward Current	I _F	30	2 0	20	mA
Pulse Forward Current*	Ifp		5 0		mA
Reverse Voltage	V_{R}	5			V
Powe r Dissipation	P _D	72	6 8	72	mW
Total Po wer Dissipation	Рто т	9 0			mW
Operatin g Temperat ure	Top r	-30 +85			$^{\circ}$
Storage Temperature	Storage Temperature Tst G		-40~+100		°C
Total Junction Temperature	Тј	1 00			$^{\circ}$

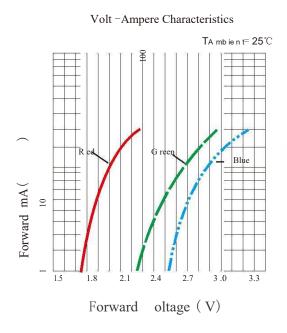
^{*} Note: Pulse Width ≤10ms, Duty cycle≤1/10

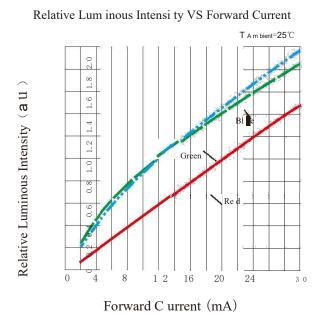
1.2 Initial Electrical /Optical C haracteristics ($T_A = 25$ °C)

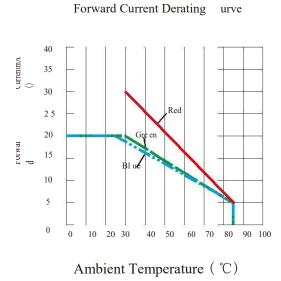
Item	Symbol	Condition	Color	Min.	Тур .	Max.	U nit
Reverse Cu rrent	I _R	V _R =5V	-	-	-	50	μА
		I _F =20mA	Red	1.8	2.0	2.4	
Forward Vo Itage	VF	I _F =12mA	Green	2.4	2.6	3.4	V
		I _F =12mA	Blue	2.6	2.8	3.6	
		I _F =20mA	Red	615	62 0	630	
D ominant Wavelength	λD	I _F =12mA	Green	515	52 0	535	nm
		I _F =12mA	Blue	465	47 0	480	
	Δλ	I _F =20mA	Red	-	-	24	
Spectrum Ra diation Bandwid th		I _F =12mA	Green	-	-	38	nm
Danawia tii		I _F =12mA	Blue	-	-	28	
Luminous Intensity	I _V	I _F =20mA	Red	475	69 0	990	
		I _F =12mA	Green	830	1200	1750	m cd
		I _F =12mA	Blue	165	24 0	350	
View Angle	2θ1/2	-	-	-	11 0	-	deg

^{*} Note: The a bove data are only for r ference, th ey come fro m the standard testing s ystem of N ationStar.

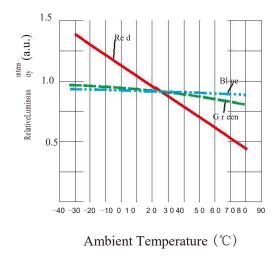
2 . TYPIC AL CHA RACTERISTICS CURVE $\mathbf{S}(1)$





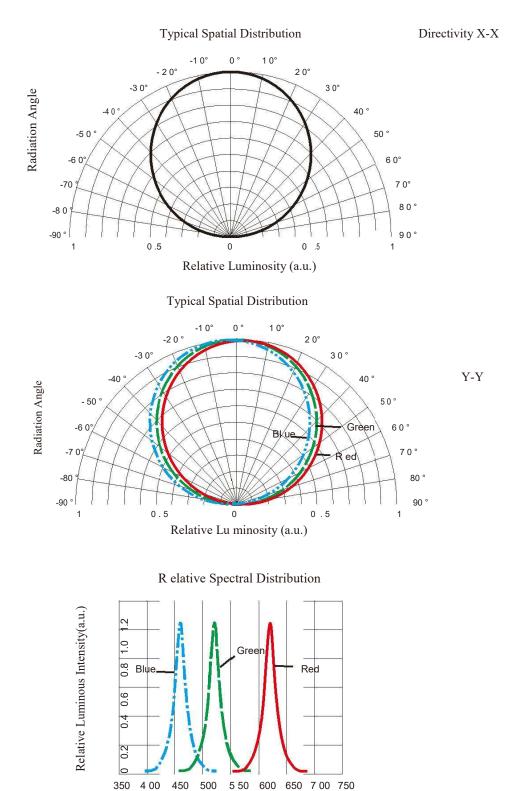


Luminous Intensity VS Ambient Tem perature



^{*} Note: The above data are collected from statistical figures that do not necessarily correspond to the actual parameters of each single LED.

2 . TYPIC AL CHAR ACTERI STICS CURVES(2)



Wevelen gth(nm)

3. RELIA BILITY

3.1 Test It em

Ite m	Reference Stan dard	Test Conditio ns	Test Duration	Faile d/ Test ed
Resistance to Soldering	JEITA E D-4701	T _{sld} = 260±5)℃, 10sec,		
Heat*	300 301	Preconditi on:30 $^\circ\!\!\!\!\!^\circ$, 70 $^\circ\!\!\!\!\!^\circ$ RH,168hr	3 reflo ws	0/1 00
Thermal Shock	MIL-STD -202G	-40°C(30 min)←→100°C(30min)	300 cycles	0/1 00
Moisture Re sistance	JEITA E D-4701 200 203	-10~65℃, 0~90%RH, 24hr/cycle	10 cycles	0/1 00
Hi gh Temperature Storage	JEITA E D-4701 200 201	T _A =100℃	1000h	0/1 00
Low Temperature Storage	JEITA E D-4701 200 202	T _A =-40°C	1000h	0/1 00
Te mperature & Humidity Storage	JEITA E D-4701 100 103	T _A = 85℃,RH= 85%	1000h	0/1 00
Room Tem perature Operatin g Life	JESD22- A108D	T _A =25℃, I _{FR} =30mA, _{FG} =15mA, I _{FB} =15mA	1000h	0/1 00
Low Temperature Operatin g Life	JESD22- A108D	T _A =-40℃, I _{FR} =30mA, I _{FG} =15mA, I _{FB} =15mA	1000h	0/1 00
Te mperature & Humidity Operatin g Life	JEITA E D-4701 100 102	$T_A = 60^\circ C$, $RH = 90 \%$, $I_FR = 20 mA$, $I_FB = 12 mA$	500 h	0/1 00
Water Pro of Test	IEC 6052 9:2001	Imme rsing in 1m water	24h	0/1 00
E lectrostatic Discharge Test	AEC(Q10 1-001)	Human body model 1000 V, (Forward and reverse each 1time)	1 cycle	0/1 00

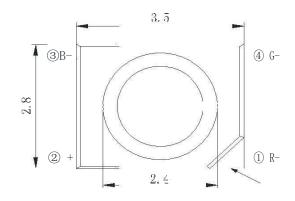
3.2 Failure Criteria(Value for single color)

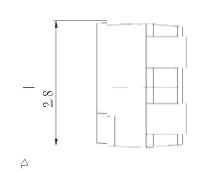
Test Item s	Sym bol	Test Conditions	Failure Cr iteria
F orward Volta ge	V _F	IF	>USL× 1.1
Reverse Curr ent	I _R	V _R	>USL× 2
Luminous Intensity	Ιγ	IF	<lsl×0 .7<="" td=""></lsl×0>
*	-	-	Dead lamps and v sual damage

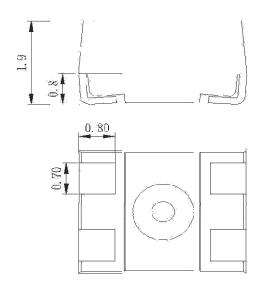
Note: Measure ments are p erformed af ter allowing the LEDs to return to room temperature.

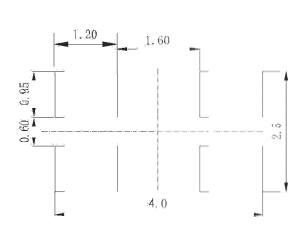
USL: Upper Specific ation limit. LSL: Low er Specification Limit.

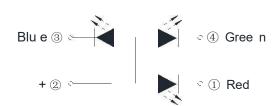
4 . OUTLINE DIMENSIONS











Recommended Soldering Pad Pat tern

A: Mark

Unit: m m

Tolerances: X.X±0. 1

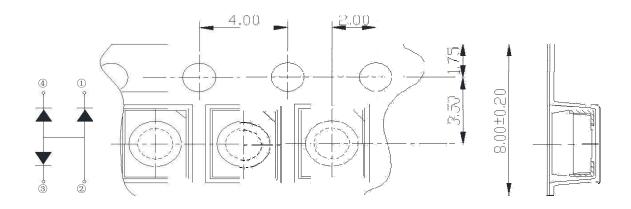
X.XX±0.05

Item	Descriptio n		
Package M aterials	Heat-resistant Polymer		
Encapsulating Resin	Epoxy Resin(with		
Materials	diffuser)		
Electrodes Materials	Ag-plated Copper Allo y		

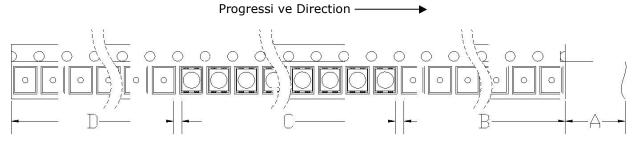
5 . PACKA GING

Unit: mm, Tolerance: ± 0.1 mm

5.1 Tape

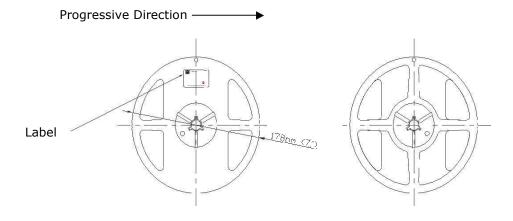


5.2 Trailer and Leader



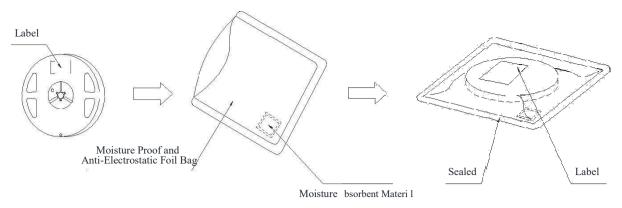
D: Traile r, Empty, 100m m; C:2000 LEDs Loaded; B: Leader, Empty: 100mm; A: Top Cover Tape: 200mm;

5.3 Reel

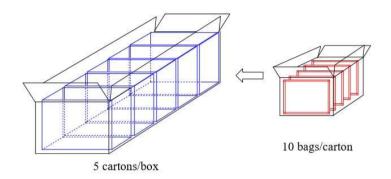


7

5 .4 Moisture-Proof & Antistatic Foil Ba g



5 .5 Cardboard Box



* Note: Do not drop or expose the box to e xternal force s as it may damage the products. Do not expose to water. The box is not water-r esistant.

Using the original package material or equivale nt in transit is recommended.

5 .6 Label E xplanatio n

TYPE: QTY:

Quantity BIN:

R ank SC: Bin

Code

LOT: Lo t Number λd:

Wavelength Range IV: Lum

inous Inten sity Range VF:

Forward Voltage Range IF:

Test Current

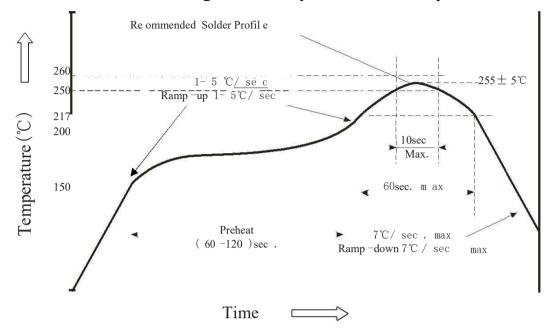
6. GUIDE LINE F OR SOL DERING

6.1 Recom mended H and Soldering Con dition

Temperature	315℃ M ax		
cSoldering Time	2sec Max		

- The package materials of the LED s hould not contact the soldering tool.
- When Sold ering, do not apply stres s to the surface resin.
- Hand soldering must n ot be perfor med more than once.

6.2 Recom mended R eflow Soldering C ondition(Lead-free Solder):



- This LED is designed to be reflow soldered on to PCB. If di p soldered, we cannot guarantee its reliability.
- Reflow soldering must not be performed more than twice.
- Stress on t he LEDs should be avoid ed during heating in soldering process.
- When solde ring, do not apply stress to the LED while the LED is hot.
- Nitrogen reflow solderi ng is recomm ended. Air flow solderin g condition s can cause optical degr adation,
 caused by heat or atmosphere.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used.(It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.)
- When using a pick and place mach ne, choose an appropri ate nozzle fo r this product.
- This product can differ in optical characteristics depending on both the number of reflow cycles and reflow temperature conditions.

7. CAUTIONS

7.1 Storage

Conditions		Tem perature	Humidity	Time
Storage B efore Opening Aluminu m Bag A fter Openin g Aluminum Bag			≤60%RH ≤60%RH	Within 1 Yea r form Deliv ery Date ≤24hours
Baking		80±5℃	-	12±1 hours

- Product co mplies with EDEC MSL 3 or equival ent, See IPC/JEDEC STD-020 for mo isture-sensitivity details .
- Absorbed moisture in LED packages can vapo rize and expand durin soldering, which can cause interface
 delaminatio n and result in optical performance degradation. Products a repacked in moisture-proof
 aluminum bags to min imize moisture absorption during transportation and storage. Included silica gelide
 siccants chainge from brown to blue if moisture had penetrated bags.
- After opening the mois ture-proof aluminum bag, the products should go through the soldering process with hin the range of the conditions stated above. Unus ed remaining LEDs should be stored with silicates desiccants in a hermetically sealed container.
- If the alum inum bag has leaked air before opening or the "Period After Openin g" storage time has been exceeded, the product s should be baked. Baking should only be done once and the reel should out of the aluminum bag when baking.
- Although the leads or electrode pads(anode and cathode)of the product are plated with Ag, prolonged exposure to corrosive environment might cau se the Ag plated the leads or electride pads to tarnish, and thus leading to difficulties in soldering. If unused LEDs remain, they must be stored in a hermetic ally sealed container.
- Do not use sulfur-conta ining materials in comm ercial prod ucts. Some materials, such as seals and adhesiv es, may contain sulfur. The contaminated plating of LEDs might cause an open circuit. Silicone rubber is recommended as a material for sells.
- To prevent water cond ensation, please avoid large temperature and humidity fluctuations for the storage conditions.
- Do not exp ose the LEDs to direct sunlight and/o r an environ ment where the temperature is high er than nor mal room temperature.

7.2 Directions for Us e

- In designing a circuit, the current through each LED die must not exceed the Absolute Maximum Rating current specified for each die. It is recommended that each LED die is driven at a constant current.
- When havin g the two or more die within this product on at the same time, the tot all power dissipation for the LED package must be within the ab solute maximum value specified in this specification.
- This product should be operated u sing forward current. E nsure that the product is not subjected to either forward or reverse voltage while it is not in use. In particular, subjecting it to continuous reverse voltage may cause migration, which may cause damage to the LED die. When used in displays that are not used for all ong time, the main power supply should be switched off for safety.
- Care must be taken to ensure that the reverse voltage will not exceed the Absolute M aximum Rating when us ing the LEDs with matrix drive.
- Ensure that excessive v oltages such as lightnin g surges are not applie d to the LED s.
- Aging is rec ommended for detecting manufactu ring and as sembly defects. In particular, ensure that excess ive current and /or voltage is not applied to the LEDs. This aging should be c onducted in environme ts where wa ter condensation does not occur.
- It is recom mended to operate the L EDs at a cur rent greater than 10% of the sorting current to stabilize the LED characteristics.
- This product can be used in indoor applications; however, when the LEDs are used in the following environments, incorporate sufficient measures into the display to prevent debris, water/moisture and gases the twill adversely affect the product.
 - where wa ter vapor is abundant, where water condensati on is likely to occur
 - where wa ter is likely to splash on to the LED s
 - where frost is likely to form on the surface of the LEDs(e.g. freezer, ice skating rink, etc)
 - where du st, dirt, de bris, loose metallic materials and/o r gases tha t will adve sely affect the product are present
- In areas where hydrog en sulfide, which is a sulfide-based g as, is present(e.g. hot s prings and volcanic are as), and where salt is abun dant(e.g. coastal areas), the life may be shorte ned.
- When this product is u sed for dis plays that will be installed outside: the LEDs should be covered to avoid exposure to outdoor environments in conjunction with sufficient measures against direct sunlight, wet or damp conditions, and salt damage.
- When powe r is applied for the first time after installation, t he display sh ould not be powered an 100% watt age since the L EDs may h ave absorbed moisture. Before n ormal use of this display, operate the display at approximately 20% wattage for an initial time period.
- If the displa y units will be rented, those unites should be selected carefully to ensure that the display as a whole will appear the same color and brightness.
- If the displa y units are loaded onto and/or tran sported by ship, the dam p environment on the vessel will cause condensation; the display units should be packaged to prevent moisture absorption.
- If a display that has bee n, or is being, used is re located, it i possible that degradation of the LED has occurred. When trans porting this display, provide sufficient protection for the L EDs in addition to the moisture-pr oof packaging for the display. When this display is reinstalled, ensure to follow the installation instructions for environments and use.

7.3 Handing Precaut ions

- Do not han die the LED s with bare hands as it will conta inate the LED surface and may affect the optical characteristics: it might cause the LED to be deformed and/or the wire to break, which will case the LED not to illuminate. The lead could also cause an injury.
- When handing the prod uct with tweezers, be careful not to apply excessive force to the resin. Otherwise, the resin can be cut, chipp ed, delamin ate or defor med, causin g wire-bond breaks and catastrophi c failures.
- Dropping the product m ay cause d amage.
- Do not stack assemble d PCBs toget her. Failure to comply can cause the resin portion of the product to be cut, chipped, de laminated a nd/or defor med. It may cause wire to break, leading to catastrophic failures.

7.4 Design Consideration

- PCB warpag e after mounting the pr oducts onto a PCB can cause the pack age to break. The LED should be placed in a way to minimize the stress on the LEDs due to PCB bow and twist.
- The position and orient ation of the LEDs affect how much mechanical stress is exert ed on the LEDs placed near
 the score lines. The LED should be placed in a way to minimize the stress on the LEDs due to board
 flexing.
 Board separation must be performed using special jigs, not using hand s.

7.5 Electro static Discharge(ESD)

- The products are sensitive to static electricity or surge volt age. ESD can damage a die and its reliability. W hen handling the products, the following measures against elec trostatic discharge are strongly rec ommended:
 - Eliminatin g the charge
 - Grounded wrist strap, ESD footw ear, clothes, and floors
 - Grounded workstatio n equipment and tools
 - ESD table /shelf mat made of conductive materials
- Ensure that tools (e.g. soldering iro ns), jigs and machines that are bein g used are properly grounded and that proper grounding techniques are used in work areas. For devices/equi pment that mount the LEDs, protect ion against surge voltages should also be used.
- If tools or equipment contain insulating materials such as glass or plastic, the following me asures agai nst electrostatic discharge are strongly recommen ded:
 - Dissipatin g static charge with con ductive ma terials
 - Preventing charge generation with moisture
 - Neutralizing the char ge with ioniz ers
- The custom er is advised to check if the LED s are damaged by ESD, when performing the characteristics
 inspection of the LEDs in the applic ation. Dam age can be detected with a forward voltage measurement o r
 a light-up test at low current (≤1mA).
- LEDs with E SD-damaged dice (i.e. o ther than red) may have an increase d leakage c urrent, current flow at a low voltage, or no longer illuminate at a low current. Failure criteria: V_F<2.0V at I_F=0.5mA.

7.6 Therma I Manage ment

- Proper ther mal management is an important when designing products with LED s. LED die temperatur e is
 affected by PCB thermal resistance and LED spa cing on the board. Please design pro ducts in a way that the LED
 die temper ature does n ot exceed the maximum junction to mperature T₁).
- Drive current should be determine d for the sur rounding a mbient temperature (T_A) to dissipate the heat form the product.

7.7 Cleaning

- The LEDs should not be cleaned with water, benzene, and/or thinner.
- If required, isopropyl alcohol (IPA) hould be used. Other solvents may ause prema ture failure to the LEDs due to the dam age to the re sin portion. The effects of such solvents should be verified p rior to use. In addition, the use of CFC s such as Fr eon is heavily regulated.
- When dust and/or dirt adheres to the LEDs, so ak a cloth w ith Isoprop yl alcohol (I PA), then squeeze it before wiping the LEDs.
- Ultrasonic cleaning is not recommended since it may have adverse effects on the LEDs depending on the ultrasonic power and how LED is assembled. If ultrasonic cleaning must be used, the customer is advised to make sure the LEDs will not be damaged prior to cleaning.

7.8 Eye Safety

- Please proceed with cau tion when viewing directly any LEDs driven at high current, or viewing L EDs with optical instrument s which may greatly inc ease the damages to y our eyes.
- Viewing a flashing light may cause eye discomfort. When incorporating the LED in to your product, please be careful to avoid adverse effects on the human body caused by light stimulation.

7.9 Others

- The LEDs described in this brochur e are intended to be use d for ordinary electroni c equipment (such as office equipment, communications equipment, measurement instrument and household appliances). Con sult NATIONSTA R's sales st aff in advance for information on the applications in which exceptional quality and reliability are required, particularly when the failure or malfunction of the LEDs may directly je opardize life or health (such as for airplanes, aerospace, submersible repeaters, nuclear reactor control system, automobiles, traffic control equipment, life support systems and safety devices).
- The custom er shall not reverse engineer by disassembling or analysis of the LEDs without having prior written consent from NATIONSTAR. When defective LE Ds are found, the custo mer shall in form NATIO NSTAR directly before disassembling or analysis.
- The specific ations and appearance of this specification. Bot h the custo mer and NATIONSTAR will agree on the official spec ifications of supplied products before the volume production of a program begins.